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MULTI-PROJECT FAN-OUT WAFER LEVEL PACKAGING FOR EUROPRACTICE

Early Access MPFOWLP Run available mid 2019
For more information please contact us!

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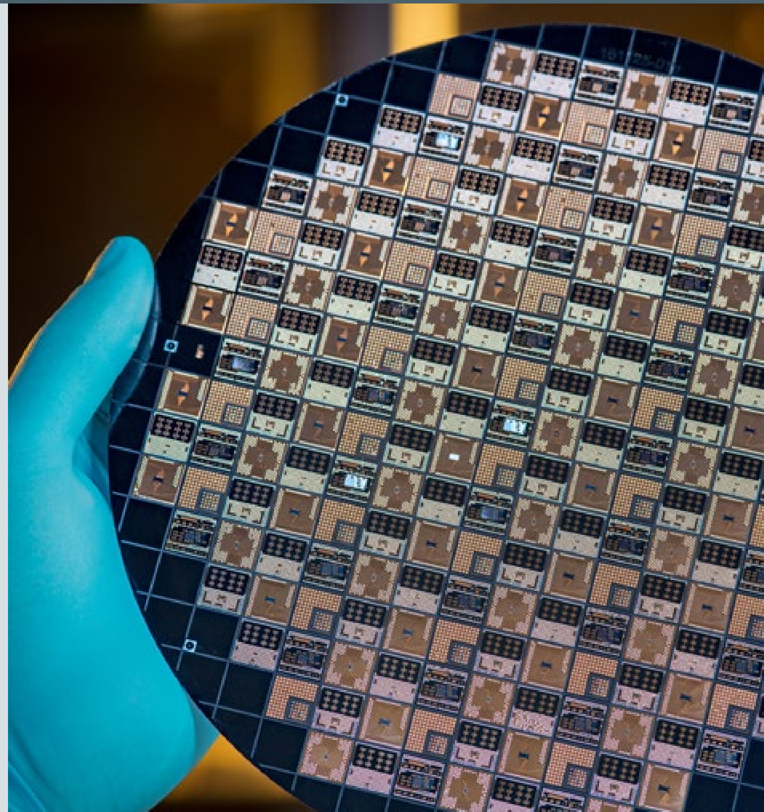


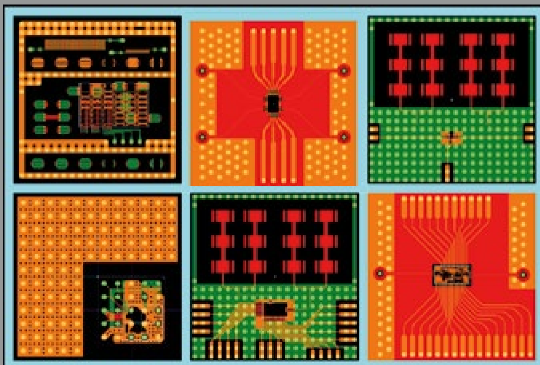
MPFOWL PACKAGE SPECIFICATION

- Die delivery: WafflePack, wafer, wheel
- Die size: 1.5 – 7 mm edge length
- Die thickness: 200 – 300 µm
- Package thickness: 450 µm
- Package size: 10x10 mm², smaller package size possible with extra effort
- Metal layers: 2
- Integration of e.g. antennas and passive structures in RDL
- Pin-out: BGA
  - Pitch: 500 µm
  - Ball size: 300 µm
  - Solder: SnAgCu
- Defined packaging materials

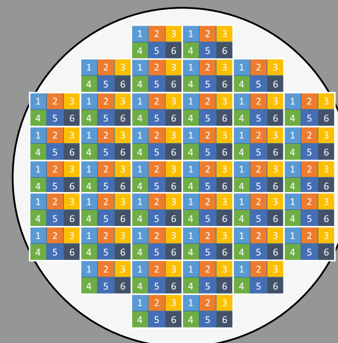
DESIGN RULES & MATERIALS

Multi-project wafer processing is an established approach in semiconductor manufacturing for fast and low cost prototyping. This idea is now transferred to fan-out wafer level packaging. Here dies from different sources or different technologies with varying thickness and size can be handled and packaged with one integration technology. This offers a path to a well adopted technology, especially for RF applications.

LOW VOLUME PROTOTYPING MULTI PROJECT FAN-OUT WAFER LEVEL PACKAGING

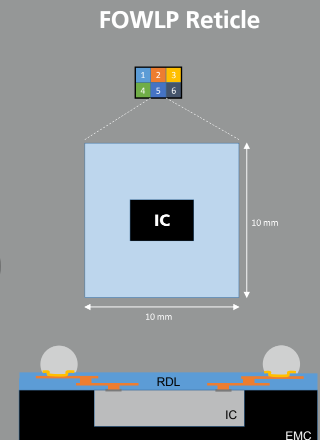


RF package design example in cooperation with IHP



Multi Project Fan-out Wafer

FOWLP Reticle



FOWLP Package